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### **RG12864B-BIW-V**

**CUSTOMER** 

### **SPECIFICATION**

<b>APPROVED BY:</b>		
( FOR CUSTOMER USE ONLY )		
	PCB VERSION:	<b>DATA:</b>

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY
ISSUED DATE:			

## **RG12864B-BIW-V**

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# **1. Specification Revision History**

	RECORDS OF REVISION										
VERSION	DATE	REVISED PAGE NO.	Note								
1	2008.1.23		First issue								

### 2. General Specification

The Features of the Module is description as follow:

■ Module dimension: 75.0 x 52.7 x 8.9 (max.) mm<sup>3</sup>

■ View area: 60.0 x 32.6 mm<sup>2</sup>

■ Active area: 55.0 x 27.48 mm<sup>2</sup>

■ Number of Dots: 128 x 64

Dot size:  $0.39 \times 0.39 \text{ mm}^2$ 

■ Dot pitch: 0.43 x 0.43 mm<sup>2</sup>

■ LCD type: STN Negative, Transmissive, blue

■ Duty: 1/64

■ View direction: 6 o'clock

■ Backlight Type: LED, White

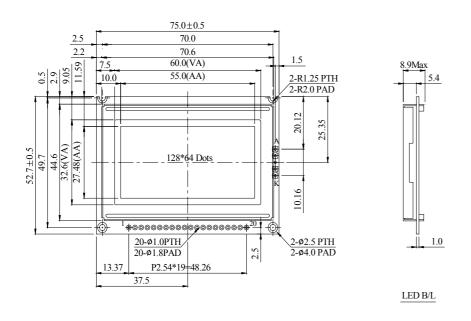
### 3. Module Classification Information

Item	Description								
1	Brand: Raysta	ar Optronics Inc.							
2	Display Type	C: Character Type,							
2	Display Type	G: Graphic Type							
3	Display Font:	128 x64 Dots							
4	Serials Code.								
		P: TN Positive, Gray							
		N: TN Negative,							
		G: STN Positive, Gray							
5	LCD Mode	Y: STN Positive, Yellow Green	n						
		B: STN Negative, Blue							
		F: FSTN Positive							
		T: FSTN Negative							
		A: Reflective, N.T, 6:00	K: Transflective, W.T,12:00						
		D: Reflective, N.T, 12:00	1: Transflective, U.T,6:00						
	LCD	G: Reflective, W. T, 6:00	4: Transflective, U.T.12:00						
	Polarizer	J: Reflective, W. T, 12:00	C: Transmissive, N.T,6:00						
6	Type/	0: Reflective, U. T, 6:00	F: Transmissive, N.T,12:00						
	Temperature range/ View	3 : Reflective, U. T, 12:00	I: Transmissive, W. T, 6:00						
	direction	B: Transflective, N.T,6:00	L: Transmissive, W.T,12:00						
		E: Transflective, N.T.12:00	2: Transmissive, U. T, 6:00						
		H: Transflective, W.T,6:00	5 : Transmissive, U.T,12:00						
		N: Without backlight	Y: LED, Yellow Green						
	5 11:1	P: EL, Blue green	A: LED, Amber						
7	Backlight	T: EL, Green	W: LED, White						
	Type	D: EL, White	O: LED, Orange						
		F: CCFL, White	G: LED, Green						
8	Special Code V: Build in Negative voltage output								

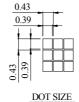
### **4. Interface Pin Function**

Pin No.	Symbol	Level	Description
1	VDD	5.0V	Power supply (+5V)
2	$V_{SS}$	0V	Power supply (GND)
3	V <sub>o</sub>	(Variable)	Contrast Adjustment
4	DB0	H/L	Data bus line
5	DB1	H/L	Data bus line
6	DB2	H/L	Data bus line
7	DB3	H/L	Data bus line
8	DB4	H/L	Data bus line
9	DB5	H/L	Data bus line
10	DB6	H/L	Data bus line
11	DB7	H/L	Data bus line
12	CS1	L	Select Column 1~ Column 64
13	CS2	L	Select Column 65~ Column 128
14	RST	L	Reset signal
15	R/W	H/L	H: Read (MPU←Module), L: Write (MPU→Module)
16	D/I	H/L	H: Data, L: Instruction
17	Е	Н	Enable signal
18	Vee	_	Negative Voltage output
19	A	_	Power Supply for LED (+)
20	K	_	Power Supply for LED (- )

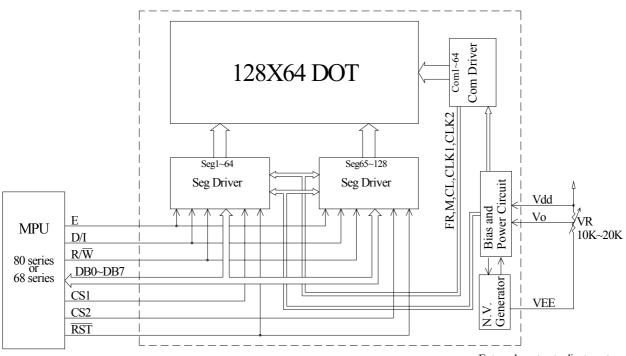
## 5. Outline Dimension & Block Diagram



PIN NO.	SYMBOL
1	Vdd
2	Vss
3	Vo
4	DB0
5	DB1
6	DB2
7	DB3
8	DB4
9	DB5
10	DB6
11	DB7
12	CS1
13	CS2
14	RST
15	R/W
16	$D/\overline{I}$
17	Е
18	Vee
19	A
20	K



The non-specified tolerance of dimension is  $\pm 0.3$ mm.



External contrast adjustment.

## **6. Display Control Instruction**

The display control instructions control the internal state of the NT7108. Instruction is received from MPU to NT7108 for the display control. The following table shows various instructions.

Instruction	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Display on/off	L	L	L	L	Н	Н	Н	H H L/H		L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON
Set address (Y address)	L	L	L	Н		Υ	addres	ss (0-6	3)		Sets the Y address in the Y address counter.
Set page (X address)	L	L	Н	L	Н	Н	Н	Page (0-7)			Sets the X address at the X address register.
Display Start line (Z address)	L	L	Н	Н		Display start line (0-63)					Indicates the display data RAM displayed at the top of the screen.
Status read	L	Н	Busy	L	On/ Off	Reset	L L L L		L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset	
Write display data	Н	L				Write data					Writes data (DB0: 7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.
Read display data	Н	Н				Read data					Reads data (DB0: 7) from display data RAM to the data bus.

### 7. Detailed Explanation

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0. Though the data is not on the screen with D=0, it remains in the display data RAM. Therefore, you can make it appear by changing D=0 into D=1.

#### **SET ADDRESS (Y ADDRESS)**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address (AC0-AC5) of the display data RAM is set in the Y address counter. An address is set by instruction and increased by 1 automatically by read or write operations of display data.

#### **SET PAGE (X ADDRESS)**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	0	1	1	1	AC2	AC1	AC0

X address (AC0-AC2) of the display data RAM is set in the X address register. Writing or reading to or from MPU is executed in this specified page until the next page is set.

#### **DISPLAY START LINE (Z ADDRESS)**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	1	1	AC5	AC4	AC3	AC2	AC1	AC0

Z address (AC0-AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen. When the display duty cycle is 1/64 or others (1/32-1/64), the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

#### **STATUS READ**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	0	ON/OFF	RESET	0	0	0	0

#### • BUSY

When BUSY is 1, the Chip is executing internal operation and no instructions are accepted. When BUSY is 0, the Chip is ready to accept any instructions.

#### • ON/OFF

When ON/OFF is 1, the display is OFF.

When ON/OFF is 0, the display is ON.

#### • RESET

When RESET is 1, the system is being initialized.

In this condition, no instructions except status read can be accepted. When RESET is 0, initializing has finished and the system is in usual operation condition.

#### WRITE DISPLAY DATA

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	D7	D6	D5	D4	D3	D2	D1	D0

Writes data (D0-D7) into the display data RAM. After writing instruction, Y address is increased by 1 automatically.

#### **READ DISPLAY DATA**

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

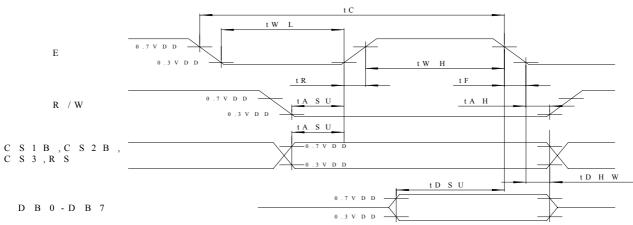
Reads data (D0-D7) from the display data RAM. After reading instruction, Y address is increased by 1 automatically.

## 8. Timing Characteristics

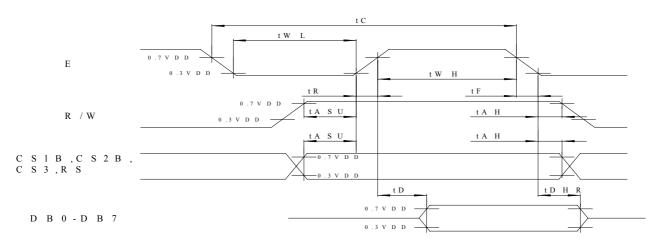
MPU Interface

 $(T=25^{\circ}C, VDD=+5.0V\pm0.5)$ 

Characteristic	Symbol	Min	Тур	Max	Unit
E cycle	teye	1000	_	_	ns
E high level width	twhE	450	_	_	ns
E low level width	twlE	450	_	_	ns
E rise time	tr	_	_	25	ns
E tall time	tf	_	_	25	ns
Address set-up time	tas	140	_	_	ns
Address hold time	tah	10	_	_	ns
Data set-up time	tdsw	200	_	_	ns
Data delay time	tddr	_	_	320	ns
Data hold time (write)	tdhw	10	_	_	ns
Data hold time (read)	tdhr	20	_	_	ns



MPU Read Timing



MPU Write Timing

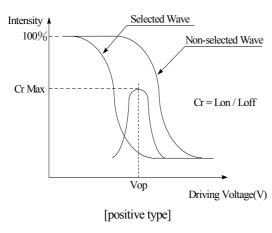
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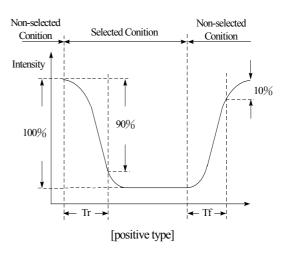
### 9. Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
View Angle	(V) θ	CR≧2	20	_	40	deg
, iew imgie	(H) φ	CR≧2	-30	_	30	deg
Contrast Ratio	CR	_	_	3	_	_
Response Time	T rise	_	_	150	200	ms
	T fall	_	_	150	200	ms

#### **Definition of Operation Voltage (Vop)**

### **Definition of Response Time (Tr, Tf)**





#### **Conditions:**

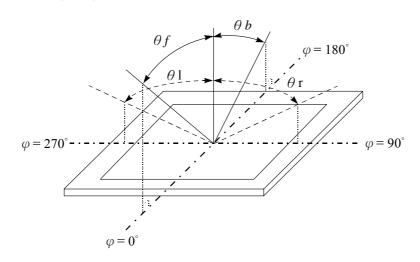
Operating Voltage: Vop

Viewing Angle( $\theta$ ,  $\varphi$ ):  $0^{\circ}$ ,  $0^{\circ}$ 

Frame Frequency: 64 HZ

Driving Waveform: 1/N duty, 1/a bias

### Definition of viewing angle( $CR \ge 2$ )



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## 10. Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	$T_{OP}$	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	$T_{ST}$	-30	_	+80	$^{\circ}\!\mathbb{C}$
Input Voltage	V <sub>I</sub>	0	_	$V_{ m DD}$	V
Supply Voltage For Logic	$V_{ m DD}$	0	_	6.7	V
Supply Voltage For LCD	V <sub>DD</sub> -V <sub>LCD</sub>	0	_	16.7	V

### 11. Electrical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
Supply Voltage For Logic	$V_{DD}$ - $V_{SS}$	_	4.5	5.0	5.5	V
		Ta=-20°C	_	_	9.6	V
Supply Voltage For LCD	$ m V_{DD} extbf{-}V_0$	Ta=25°℃	_	8.0	_	V
		Ta=+70°C	7.6	_	_	V
Input High Volt.	$V_{\mathrm{IH}}$	_	2.0	_	$V_{\mathrm{DD}}$	V
Input Low Volt.	$V_{\rm IL}$	_	0	_	0.8	V
Output High Volt.	$V_{\mathrm{OH}}$	_	2.4	_	$V_{DD}$	V
Output Low Volt.	$V_{OL}$	_	0	_	0.4	V
Supply Current	$I_{DD}$	_	3.0	4.0	5.0	mA

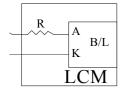
## 12. Backlight Information

### **Specification**

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	48	60	90	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	_
Reverse Voltage	VR	_	_	5	V	_
Luminous Intensity	IV	150	200	_	cd/m <sup>2</sup>	ILED=60mA
Wave Length	λр	_		_	nm	ILED=60mA
Life Time	_	_	50K	_	Hr.	ILED=60mA
Color	White					

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

.Drive from pin19,pin20



### 13. Reliability

### Content of Reliability Test (wide temperature, -20°C~70°C)

	<b>Environmental Test</b>		
Test Item	Content of Test	<b>Test Condition</b>	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation  -20°C 25°C 70°C  30min 5min 30min 1 cycle	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 15mm  Vibration Frequency: 10~55Hz  One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal Temperature and humidity after remove from the test chamber.

Note3: Vibration test will be conducted to the product itself without putting it in a container.

# 14. Inspection specification

NO	Item	Criterion	AQL				
01	Electrical Testing	<ul> <li>1.1 Missing vertical, horizontal segment, segment contrast defect.</li> <li>1.2 Missing character, dot or icon.</li> <li>1.3 Display malfunction.</li> <li>1.4 No function or no display.</li> <li>1.5 Current consumption exceeds product specifications.</li> <li>1.6 LCD viewing angle defect.</li> <li>1.7 Mixed product types.</li> <li>1.8 Contrast defect.</li> </ul>					
02	Black or white spots on LCD (display only)	<ul> <li>2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present.</li> <li>2.2 Densely spaced: No more than two spots or lines within 3mm</li> </ul>	2.5				
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y)/2$ $X$ $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$ $0$ 3.2 Line type : (As following drawing) $C = A                                  $					
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	2.5				

NO	Item	Criterion	AQL
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination	
06	Chipped glass	Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length: 6.1 General glass chip: 6.1.1 Chip on panel surface and crack between panels:	2.5

NO	Item	Criterion	AQL
06	Glass	Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:	2.5
		$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	

NO	Item	Criterion	AQL		
07	Cracked glass	The LCD with extensive crack is not acceptable.			
08	Backlight elements	<ul> <li>8.1 Illumination source flickers when lit.</li> <li>8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards.</li> <li>8.3 Backlight doesn't light or color wrong.</li> </ul>			
09	Bezel	<ul><li>9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination.</li><li>9.2 Bezel must comply with job specifications.</li></ul>			
10	PCB、COB	<ul> <li>10.1 COB seal may not have pinholes larger than 0.2mm or contamination.</li> <li>10.2 COB seal surface may not have pinholes through to the IC.</li> <li>10.3 The height of the COB should not exceed the height indicated in the assembly diagram.</li> <li>10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places.</li> <li>10.5 No oxidation or contamination PCB terminals.</li> <li>10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts.</li> <li>10.7 The jumper on the PCB should conform to the product characteristic chart.</li> <li>10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down.</li> <li>10.9 The Scraping testing standard for Copper Coating of PCB</li> </ul>	2.5 2.5 0.65 2.5 2.5 0.65 2.5 2.5 2.5		
11	Soldering	<ul> <li>11.1 No un-melted solder paste may be present on the PCB.</li> <li>11.2 No cold solder joints, missing solder connections, oxidation or icicle.</li> <li>11.3 No residue or solder balls on PCB.</li> <li>11.4 No short circuits in components on PCB.</li> </ul>	2.5 2.5 2.5 0.65		

NO	Item	Criterion		
12	General appearance	<ul> <li>12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.</li> <li>12.2 No cracks on interface pin (OLB) of TCP.</li> <li>12.3 No contamination, solder residue or solder balls on product.</li> <li>12.4 The IC on the TCP may not be damaged, circuits.</li> <li>12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it cause the interface pin to sever.</li> <li>12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.</li> <li>12.7 Sealant on top of the ITO circuit has not hardened.</li> <li>12.8 Pin type must match type in specification sheet.</li> <li>12.9 LCD pin loose or missing pins.</li> <li>12.10 Product packaging must the same as specified on packaging specification sheet.</li> <li>12.11 Product dimension and structure must conform to product specification sheet.</li> </ul>	2.5 0.65 2.5 2.5 2.5 2.5 0.65 0.65 0.65	

### 15. Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3)Don't disassemble the LCM.
- (4)Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7)Storage: please storage in anti-static electricity container and clean environment.

### 16. Material List of Components for RoHs

1. RAYSTAR Optronics Inc., hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

### 2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250°C,30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. : 235±5°€;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.



Page: 1

LCM Sample Estimate Feedback Sheet					
Module Number :					
1 · Panel Specification :					
1. Panel Type:	☐ Pass	□ NG ,			
2. View Direction:	☐ Pass	□ NG ,			
3. Numbers of Dots:	☐ Pass	□ NG ,			
4. View Area:	☐ Pass	□ NG ,			
5. Active Area:	☐ Pass	□ NG ,	<u></u>		
6.Operating Temperature:	☐ Pass	□ NG ,	<del></del>		
7. Storage Temperature:	☐ Pass	□ NG,			
8.Others:					
2 · Mechanical Specification	:				
1. PCB Size:	☐ Pass	□ NG ,			
2.Frame Size:	☐ Pass	□ NG,			
3.Materal of Frame:	☐ Pass	□ NG ,			
4.Connector Position:	☐ Pass	□ NG ,			
5.Fix Hole Position:	☐ Pass	□ NG ,			
6.Backlight Position:	☐ Pass	□ NG ,			
7. Thickness of PCB:	☐ Pass	□ NG ,			
8. Height of Frame to PCB:	☐ Pass	□ NG ,			
9.Height of Module:	☐ Pass	□ NG ,			
10.Others:	☐ Pass	□ NG ,			
3 · <u>Relative Hole Size</u> :					
1.Pitch of Connector:	☐ Pass	□ NG ,			
2.Hole size of Connector:	☐ Pass	□ NG ,			
3. Mounting Hole size:	☐ Pass	□ NG ,			
4. Mounting Hole Type:	☐ Pass	□ NG ,			
5.Others:	☐ Pass	□ NG ,			
4 · <u>Backlight Specification</u> :					
1.B/L Type:	☐ Pass	□ NG ,	<del></del>		
2.B/L Color:	☐ Pass	□ NG ,			
3.B/L Driving Voltage (Reference for LED Type):   Pass NG,					
4.B/L Driving Current:	☐ Pass	□ NG,			
5.Brightness of B/L:	☐ Pass	□ NG ,			
6.B/L Solder Method:	☐ Pass	□ NG ,			
7.Others:	☐ Pass	□ NG,			



Page: 2

Module Number :					
5 · Electronic Characteristic	s of Module	<u>e</u> :			
1.Input Voltage:	☐ Pass	□ NG ,			
2.Supply Current:	☐ Pass	□ NG ,			
3.Driving Voltage for LCD:	☐ Pass	□ NG ,			
4.Contrast for LCD:	☐ Pass	□ NG ,			
5.B/L Driving Method:	☐ Pass	□ NG ,			
6.Negative Voltage Output:	☐ Pass	□ NG ,			
7.Interface Function:	☐ Pass	□ NG ,			
8.LCD Uniformity:	☐ Pass	□ NG ,			
9.ESD test:	☐ Pass	☐ NG ,			
10.Others:	☐ Pass	□ NG ,		<del></del> _	
6 · <u>Summary</u> :					
G-1					
Sales signature:					
Customer Signature : _			Date: / /	-	